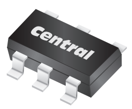
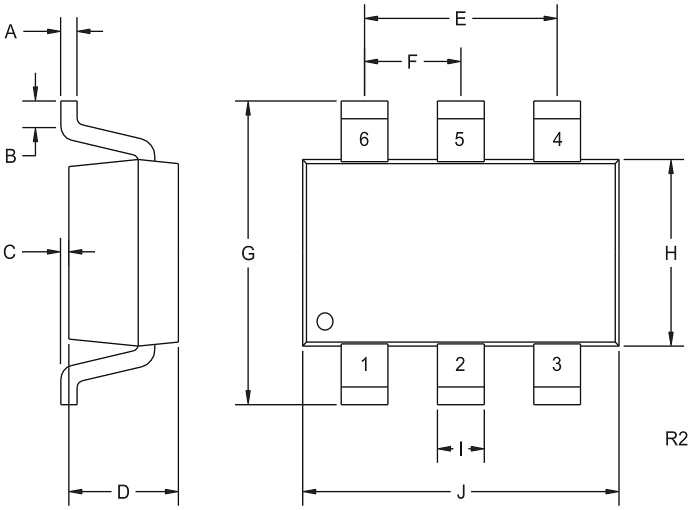
Package Details

SOT-26 Case



Central Semiconductor Corp.

Mechanical Drawing



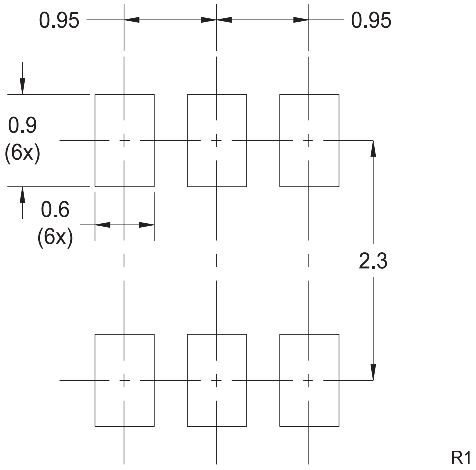
DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.004	0.007	0.11	0.19
B	0.016	-	0.40	-
C	-	0.004	-	0.10
D	0.039	0.047	1.00	1.20
E	0.074	0.075	1.88	1.92
F	0.037	0.038	0.93	0.97
G	0.102	0.118	2.60	3.00
H	0.059	0.067	1.50	1.70
I	0.016		0.41	
J	0.110	0.118	2.80	3.00

SOT-26 (REV: R2)

Lead Code:
Reference individual
device datasheet.

Part Marking: 3 Character Alpha/Numeric Code

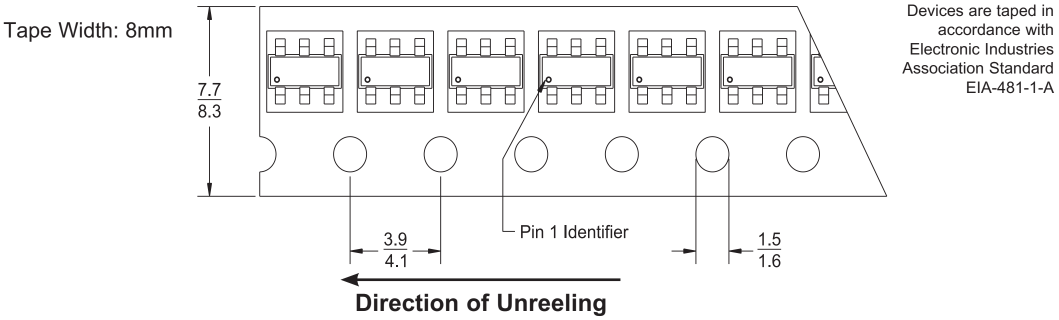
Mounting Pad Geometry (Dimensions in mm)



Package Details

SOT-26 Case

Tape Dimensions and Orientation (Dimensions in mm)



Packaging Base

7” Reel = 3,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

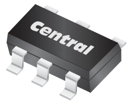
Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	27,000	9x9x5	23x23x13	4	2
	18	54,000	9x9x9	23x23x23	7	4
	40	120,000	21x9x9	53x23x23	14	7
	108	324,000	27x9x17	69x23x43	39	18

Ordering Information

- For devices taped and reeled on 7” reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

Material Composition Specification

SOT-26 Case



Device average mass . . . . **15.8 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.54%	0.24	Si	7440-21-3	1.54%	0.243	15,381
bond wire	gold	0.06%	0.01	Au	7440-57-5	0.06%	0.009	570
leadframe	copper w/ silver plating	40.4%	6.38	Cu	7440-50-8	39.91%	6.305	399,076
				Ag	7440-22-4	0.49%	0.078	4,937
encapsulation*	EMC	53.67%	8.48	silica	7631-86-9	39.71%	6.273	397,050
				epoxy resin	Proprietary	12.49%	1.973	124,881
				Sb_2O_3	1309-64-4	1.08%	0.17	10,760
				TBBA	79-94-7	0.27%	0.043	2,722
				carbon	1333-86-4	0.13%	0.021	1,329
	EMC GREEN	53.67%	8.48	silica	60676-86-0	35.88%	5.668	358,756
				epoxy resin	29690-82-2	8.15%	1.287	81,485
				phenol resin	9003-35-4	4.09%	0.646	40,881
				carbon black	1333-86-4	0.28%	0.044	2,781
				metal hydroxide	1309-42-8	5.28%	0.835	52,840
plating**	tin/lead process	4.33%	0.68	Sn	7440-31-5	3.4%	0.537	33,989
				Pb	7439-92-1	0.94%	0.148	9,368
	matte tin	4.33%	0.68	Sn	7440-31-5	4.33%	0.684	43,294

*EMC GREEN molding compound is Halogen-Free.
**For Lead Free plating, add suffix “PB FREE” to part number.
For Tin/Lead plating, add suffix “TIN/LEAD” to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R7 (16-July 2018)